

Clean Version Of Amended Claims

34. (twice amended) A test fixture for testing a semiconductor die comprising:

a plate for receiving the die;

a cover attached to the plate for retaining the die therebetween; and

a tape placed between the plate and the cover for electrically connecting the die to a test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

with the connector, and at least a portion of the trace extending beyond a confine of the fixture, and with the bump, the trace, and the connector configured to directly connect the test circuitry to the contact on the die.

35. (twice amended) The fixture of claim 34 wherein the film comprises polyamide.

36. (amended) The fixture of claim 34 wherein the plate includes a die receiving cavity configured to receive the die.

37. (amended) The fixture of claim 34 further comprising an elastomeric biasing member between the plate and the cover for biasing the bump against the contact.

38. (amended) The fixture of claim 34 further comprising a clamp for securing the plate to the cover.

39. (twice amended) A test fixture for testing a semiconductor die comprising:

a plate for receiving the die;

a cover attached to the plate for retaining the die on the plate; and

a tape for electrically connecting the die to a test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

with a first portion of the film placed between the plate and the cover and biased against the die;

with a second portion of the film and the connector extending beyond a confine of the fixture, and with the bump, the trace and the connector configured to directly connect the test circuitry to the contact on the die.

40. (amended) The test fixture of claim 39 further comprising a compressible elastomeric pad between the plate and the cover configured to bias the first portion of the film against the die.

41. (amended) The test fixture of claim 39 wherein the film comprise polyamide and the bump comprises solder.

43. (twice amended) A test fixture for testing a semiconductor die comprising:

a plate for receiving the die;

a cover attached to the plate for retaining the die on the plate; and

a tape for electrically connecting the die to a test circuitry, the tape comprising a plastic film, a bump on the film for physically and electrically contacting a

contact on the die, a conductive trace on the film in electrical communication with the bump, and an electrical connector in electrical communication with the trace and connectable to the test circuitry;

a compressible elastomeric pad between the plate and the cover for biasing the bump against the contact;

with a first portion of the film placed between the plate and the cover and biased against the die by the pad;

with a second portion of the film and the connector extending beyond a confine of the fixture, and with the bump, the trace, and the connector configured to directly connect the test circuitry to the contact on the die.

44. (amended) The test fixture of claim 43 wherein the bump comprises solder.

45. (amended) The test fixture of claim 43 wherein the plate includes a cavity for retaining the die.

46. (amended) The test fixture of claim 43 wherein the plate includes a cavity and a spacer member within the cavity for retaining the die.